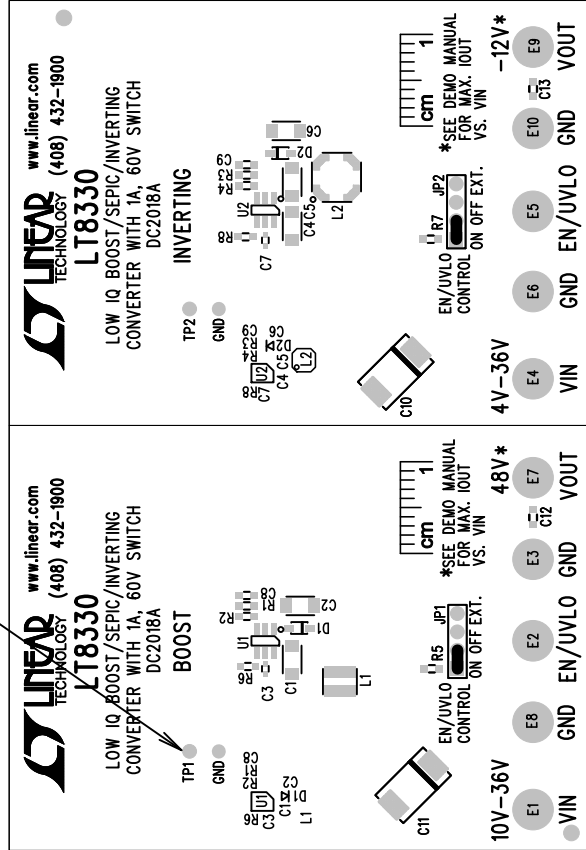
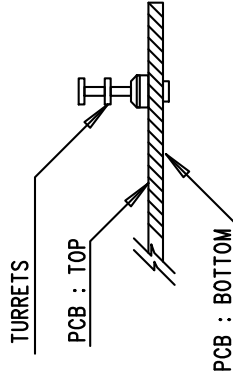


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.
7. TEST POINT(4 PLCS) SHOULD BE FREE OF SOLDER.



CAUTION :

BREAK BOARDS INTO SETS (TWO BOARDS TOGETHER) LIKE THE DRAWING ABOVE.
DO NOT BREAK BOARD INDIVIDUALLY.



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TITLE: TOP ASSEMBLY DRAWING

LOW IQ BOOST/SEPIC/INVERTING
CONVERTER WITH 1A, 60V SWITCH

SIZE	IC NO.	LT8330ES6	REV.
N/A	DEMO CIRCUIT	2018A	4
FILENAME:	DC2018A-4.PCB	SHT 1 OF 1	